

WHAT IS CLAIMED IS:

1. A through hole conduction structure of a flexible multilayer circuit board, comprising: an internal layer circuit board which can be a cable portion; and an external layer circuit board which can be a component mounting portion laminated on one side or both sides of said internal layer circuit board at a predetermined position, wherein, in said flexible multilayer circuit board having a through hole plated conduction portion formed at predetermined positions of said internal layer circuit board and said external layer circuit board, a surface protection layer formed on an external surface of a wiring pattern of said internal layer circuit board is formed in a region retreated toward the outside from a position of a through hole for the through hole plated conduction portion.

2. The through hole conduction structure of a flexible multilayer circuit board according to claim 1, wherein said surface protection layer is a cover film consisting of polyimide resin.

3. A method for forming a through hole conduction structure of a flexible multilayer circuit board comprising the steps of: forming a required wiring pattern on one side or both sides of a flexible insulating base material; preparing an internal layer circuit board having a surface protection layer formed thereto on an external surface of said wiring pattern at a position retreated toward the

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outside from a position where a predetermined through hole is to be formed; laminating an external layer circuit board which can be a component mounting portion on one side or both sides of said internal layer circuit board in association with a position of said internal layer circuit board where said through hole is formed; forming a through hole at predetermined positions of said internal layer circuit board and said external layer circuit board; and then forming a through hole plated conduction portion on an inner surface of said through hole.

4. The method for forming a through hole conduction structure of a flexible multilayer circuit board according to claim 3, wherein a cover film consisting of polyimide resin is used for said surface protection layer.

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